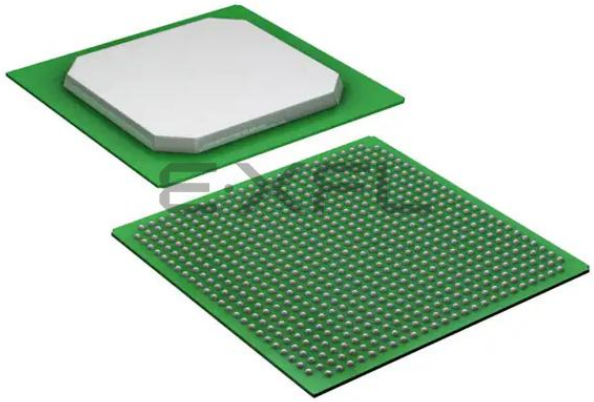

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	2076
Number of Logic Elements/Cells	33216
Total RAM Bits	483840
Number of I/O	475
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c35f672c8

PLLs

Cyclone II PLLs provide general-purpose clocking as well as support for the following features:

- Clock multiplication and division
- Phase shifting
- Programmable duty cycle
- Up to three internal clock outputs
- One dedicated external clock output
- Clock outputs for differential I/O support
- Manual clock switchover
- Gated lock signal
- Three different clock feedback modes
- Control signals

Cyclone II devices contain either two or four PLLs. Table 2–3 shows the PLLs available for each Cyclone II device.

Table 2–3. Cyclone II Device PLL Availability

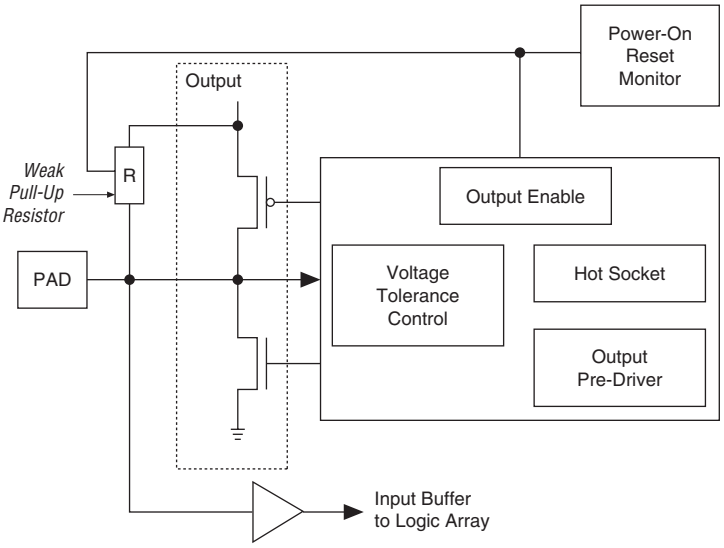
Device	PLL1	PLL2	PLL3	PLL4
EP2C5	✓	✓		
EP2C8	✓	✓		
EP2C15	✓	✓	✓	✓
EP2C20	✓	✓	✓	✓
EP2C35	✓	✓	✓	✓
EP2C50	✓	✓	✓	✓
EP2C70	✓	✓	✓	✓

Table 2–4 describes the PLL features in Cyclone II devices.

Table 2–4. Cyclone II PLL Features

Feature	Description
Clock multiplication and division	*m* / (*n* × post-scale counter) *m* and post-scale counter values (C0 to C2) range from 1 to 32. *n* ranges from 1 to 4.
Phase shift	Cyclone II PLLs have an advanced clock shift capability that enables programmable phase shifts in increments of at least 45°. The finest resolution of phase shifting is determined by the voltage control oscillator (VCO) period divided by 8 (for example, 1/1000 MHz/8 = down to 125-ps increments).
Programmable duty cycle	The programmable duty cycle allows PLLs to generate clock outputs with a variable duty cycle. This feature is supported on each PLL post-scale counter (C0-C2).
Number of internal clock outputs	The Cyclone II PLL has three outputs which can drive the global clock network. One of these outputs (C2) can also drive a dedicated PLL<#>_OUT pin (single ended or differential).
Number of external clock outputs	The C2 output drives a dedicated PLL<#>_OUT pin. If the C2 output is not used to drive an external clock output, it can be used to drive the internal global clock network. The C2 output can concurrently drive the external clock output and internal global clock network.
Manual clock switchover	The Cyclone II PLLs support manual switchover of the reference clock through internal logic. This enables you to switch between two reference input clocks during user mode for applications that may require clock redundancy or support for clocks with two different frequencies.
Gated lock signal	The lock output indicates that there is a stable clock output signal in phase with the reference clock. Cyclone II PLLs include a programmable counter that holds the lock signal low for a user-selected number of input clock transitions, allowing the PLL to lock before enabling the locked signal. Either a gated locked signal or an ungated locked signal from the locked port can drive internal logic or an output pin.
Clock feedback modes	In zero delay buffer mode, the external clock output pin is phase-aligned with the clock input pin for zero delay. In normal mode, the PLL compensates for the internal global clock network delay from the input clock pin to the clock port of the IOE output registers or registers in the logic array. In no compensation mode, the PLL does not compensate for any clock networks.
Control signals	The pllenable signal enables and disables the PLLs. The areset signal resets/resynchronizes the inputs for each PLL. The pfdena signal controls the phase frequency detector (PFD) output with a programmable gate.

Figure 4–1. Hot-Socketing Circuit Block Diagram for Cyclone II Devices



The POR circuit monitors V_{CCINT} voltage level and keeps I/O pins tri-stated until the device is in user mode. The weak pull-up resistor (R) from the I/O pin to V_{CCIO} keeps the I/O pins from floating. The voltage tolerance control circuit permits the I/O pins to be driven by 3.3 V before V_{CCIO} and/or V_{CCINT} are powered, and it prevents the I/O pins from driving out when the device is not in user mode.

For more information, see the *DC Characteristics & Timing Specifications* chapter in Volume 1 of the *Cyclone II Device Handbook* for the value of the internal weak pull-up resistors.

Figure 4–2 shows a transistor level cross section of the Cyclone II device I/O buffers. This design ensures that the output buffers do not drive when V_{CCIO} is powered before V_{CCINT} or if the I/O pad voltage is higher than V_{CCIO}. This also applies for sudden voltage spikes during hot socketing. The V_{PAD} leakage current charges the voltage tolerance control circuit capacitance.

Table 5–3. DC Characteristics for User I/O, Dual-Purpose, and Dedicated Pins (Part 1 of 2)

Symbol	Parameter	Conditions		Minimum	Typical	Maximum	Unit
V_{IN}	Input voltage	*(1)*, *(2)*		–0.5	—	4.0	V
I_i	Input pin leakage current	$V_{IN} = V_{CCIOmax}$ to 0 V *(3)*		–10	—	10	µA
V_{OUT}	Output voltage	—		0	—	V_{CCIO}	V
I_{OZ}	Tri-stated I/O pin leakage current	$V_{OUT} = V_{CCIOmax}$ to 0 V *(3)*		–10	—	10	µA
I_{CCINT0}	V_{CCINT} supply current (standby)	V_{IN} = ground, no load, no toggling inputs T_J = 25° C Nominal V_{CCINT}	EP2C5/A	—	0.010	*(4)*	A
			EP2C8/A	—	0.017	*(4)*	A
			EP2C15A	—	0.037	*(4)*	A
			EP2C20/A	—	0.037	*(4)*	A
			EP2C35	—	0.066	*(4)*	A
			EP2C50	—	0.101	*(4)*	A
			EP2C70	—	0.141	*(4)*	A
I_{CCIO0}	V_{CCIO} supply current (standby)	V_{IN} = ground, no load, no toggling inputs T_J = 25° C V_{CCIO} = 2.5 V	EP2C5/A	—	0.7	*(4)*	mA
			EP2C8/A	—	0.8	*(4)*	mA
			EP2C15A	—	0.9	*(4)*	mA
			EP2C20/A	—	0.9	*(4)*	mA
			EP2C35	—	1.3	*(4)*	mA
			EP2C50	—	1.3	*(4)*	mA
			EP2C70	—	1.7	*(4)*	mA

Table 5–3. DC Characteristics for User I/O, Dual-Purpose, and Dedicated Pins (Part 2 of 2)

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
R_{CONF} *(5) (6)*	Value of I/O pin pull-up resistor before and during configuration	V_{IN} = 0 V; V_{CCIO} = 3.3 V	10	25	50	kΩ
		V_{IN} = 0 V; V_{CCIO} = 2.5 V	15	35	70	kΩ
		V_{IN} = 0 V; V_{CCIO} = 1.8 V	30	50	100	kΩ
		V_{IN} = 0 V; V_{CCIO} = 1.5 V	40	75	150	kΩ
		V_{IN} = 0 V; V_{CCIO} = 1.2 V	50	90	170	kΩ
	Recommended value of I/O pin external pull-down resistor before and during configuration	*(7)*	—	1	2	kΩ

Notes to Table 5–3:

(1) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.

(2) The minimum DC input is –0.5 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to the voltages shown in Table 5–4, based on input duty cycle for input currents less than 100 mA. The overshoot is dependent upon duty cycle of the signal. The DC case is equivalent to 100% duty cycle.

(3) This value is specified for normal device operation. The value may vary during power-up. This applies for all V_{CCIO} settings (3.3, 2.5, 1.8, and 1.5 V).

(4) Maximum values depend on the actual T_J and design utilization. See the Excel-based PowerPlay Early Power Estimator (www.altera.com) or the Quartus II PowerPlay Power Analyzer feature for maximum values. Refer to "Power Consumption" on page 5–13 for more information.

(5) R_{CONF} values are based on characterization. $R_{CONF} = V_{CCIO}/I_{RCONF}$. R_{CONF} values may be different if V_{IN} value is not 0 V. Pin pull-up resistance values will be lower if an external source drives the pin higher than V_{CCIO}.

(6) Minimum condition at –40°C and high V_{CC}, typical condition at 25°C and nominal V_{CC} and maximum condition at 125°C and low V_{CC} for R_{CONF} values.

(7) These values apply to all V_{CCIO} settings.

Table 5–4 shows the maximum V_{IN} overshoot voltage and the dependency on the duty cycle of the input signal. Refer to Table 5–3 for more information.

Table 5–4. V_{IN} Overshoot Voltage for All Input Buffers

Maximum V_{IN} (V)	Input Signal Duty Cycle
4.0	100% (DC)
4.1	90%
4.2	50%
4.3	30%
4.4	17%
4.5	10%

Table 5–45. Maximum Output Clock Toggle Rate on Cyclone II Devices (Part 3 of 4)

I/O Standard	Drive Strength	Maximum Output Clock Toggle Rate on Cyclone II Devices (MHz)								
		Column I/O Pins *(1)*			Row I/O Pins *(1)*			Dedicated Clock Outputs		
		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
SSTL_18_ CLASS_II	16 mA	260	220	180	—	—	—	—	—	—
	18 mA	270	220	180	—	—	—	—	—	—
1.8V_HSTL_ CLASS_I	8 mA	260	220	180	260	220	180	260	220	180
	10 mA	300	250	210	300	250	210	300	250	210
	12 mA	320	270	220	320	270	220	320	270	220
1.8V_HSTL_ CLASS_II	16 mA	230	190	160	—	—	—	—	—	—
	18 mA	240	200	160	—	—	—	—	—	—
	20 mA	250	210	170	—	—	—	—	—	—
1.5V_HSTL_ CLASS_I	8 mA	210	170	140	210	170	140	210	170	140
	10 mA	220	180	150	—	—	—	—	—	—
	12 mA	230	190	160	—	—	—	—	—	—
1.5V_HSTL_ CLASS_II	16 mA	210	170	140	—	—	—	—	—	—
DIFFERENTIAL_ SSTL_2_CLASS_I	8 mA	400	340	280	400	340	280	400	340	280
	12 mA	400	340	280	400	340	280	400	340	280
DIFFERENTIAL_ SSTL_2_CLASS_II	16 mA	350	290	240	350	290	240	350	290	240
	20 mA	400	340	280	—	—	—	—	—	—
	24 mA	400	340	280	—	—	—	—	—	—
DIFFERENTIAL_ SSTL_18_CLASS_I	6 mA	260	220	180	260	220	180	260	220	180
	8 mA	260	220	180	260	220	180	260	220	180
	10 mA	270	220	180	270	220	180	270	220	180
	12 mA	280	230	190	—	—	—	—	—	—
DIFFERENTIAL_SSTL _18_CLASS_II	16 mA	260	220	180	—	—	—	—	—	—
	18 mA	270	220	180	—	—	—	—	—	—
1.8V_ DIFFERENTIAL_HSTL _CLASS_I	8 mA	260	220	180	260	220	180	260	220	180
	10 mA	300	250	210	300	250	210	300	250	210
	12 mA	320	270	220	320	270	220	320	270	220
1.8V_ DIFFERENTIAL_HSTL _CLASS_II	16 mA	230	190	160	—	—	—	—	—	—
	18 mA	240	200	160	—	—	—	—	—	—
	20 mA	250	210	170	—	—	—	—	—	—

Table 7–8. Global Clock Network Connections (Part 3 of 3)

Global Clock Network Clock Sources	Global Clock Networks															
	All Cyclone II Devices								EP2C15 through EP2C70 Devices Only							
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
DPCLK3 *(1)*																✓

Notes to Table 7–8:
(1) See the *Cyclone II Architecture* chapter in Volume 1 of the *Cyclone II Device Handbook* for more information on DPCLK pins.
(2) This pin only applies to EP2C5 and EP2C8 devices.
(3) These pins only apply to EP2C15 devices and larger. Only one of the two CDPCLK pins can feed the clock control block. The other pin can be used as a regular I/O pin.

If the dedicated clock pins are not used to feed the global clock networks, they can be used as general-purpose input pins to feed the logic array using the MultiTrack interconnect. However, if they are used as general-purpose input pins, they do not have support for an I/O register and must use LE-based registers in place of an I/O register.

Clock Control Block

Every global clock network is driven by a clock control block residing either on the top, bottom, left, or right side of the Cyclone II device. The global clock network has been optimized for minimum clock skew and delay.

Table 7–9 lists the sources that can feed the clock control block, which in turn feeds the global clock networks.

Table 7–9. Clock Control Block Inputs (Part 1 of 2)

Input	Description
Dedicated clock inputs	Dedicated clock input pins can drive clocks or global signals, such as asynchronous clears, presets, or clock enables onto a given global clock network.
Dual-purpose clock (DPCLK and CDPCLK) I/O inputs	DPCLK and CDPCLK I/O pins are bidirectional dual function pins that can be used for high fan-out control signals, such as protocol signals, TRDY and IRDY signals for PCI, or DQS for DDR, via the global clock network.

Section III. Memory

This section provides information on embedded memory blocks in Cyclone® II devices and the supported external memory interfaces.

This section includes the following chapters:

- Chapter 8, Cyclone II Memory Blocks
- Chapter 9, External Memory Interfaces

Revision History

Refer to each chapter for its own specific revision history. For information on when each chapter was updated, refer to the Chapter Revision Dates section, which appears in the complete handbook.

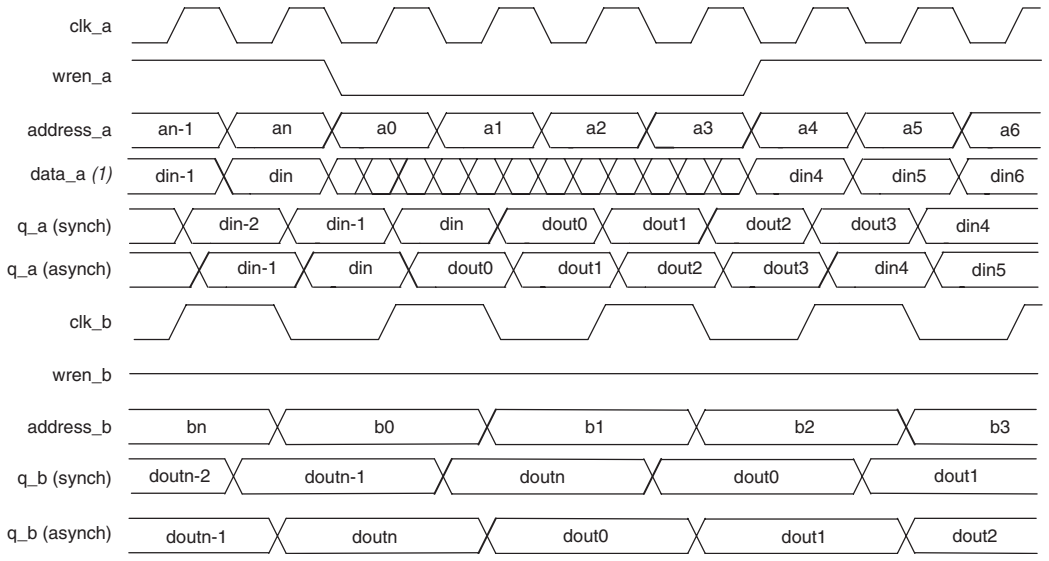
outputs, respectively. When the output registers are bypassed, the new data is available on the rising edge of the same clock cycle on which it was written. See "Read-During- Write Operation at the Same Address" on page 8–28 for waveforms and information on mixed-port read-during-write mode.

Potential write contentions must be resolved external to the RAM because writing to the same address location at both ports results in unknown data storage at that location.

For the maximum synchronous write cycle time, refer to the *Cyclone II Device Family Data Sheet* in volume 1 of the *Cyclone II Device Handbook*.

Figure 8–11 shows true dual-port timing waveforms for the write operation at port A and the read operation at port B.

Figure 8–11. Cyclone II True Dual-Port Timing Waveforms



Note to Figure 8–11:
(1) The crosses in the `data_a` waveform during write indicate "don't care."

Shift Register Mode

Cyclone II memory blocks can implement shift registers for digital signal processing (DSP) applications, such as finite impulse response (FIR) filters, pseudo-random number generators, multi-channel filtering, and auto-correlation and cross-correlation functions. These and other DSP

Table 10–2. Cyclone II 66-MHz PCI Support (Part 2 of 2)

Device	Package	–6 and –7 Speed Grades	
		64 Bits	32 Bits
EP2C8	144-pin TQFP		
	208-pin PQFP		✓
	256-pin FineLine BGA		✓
EP2C15	256-pin FineLine BGA		✓
	484-pin FineLine BGA	✓	✓
EP2C20	240-pin PQFP		✓
	256-pin FineLine BGA		✓
	484-pin FineLine BGA	✓	✓
EP2C35	484-pin FineLine BGA	✓	✓
	672-pin FineLine BGA	✓	✓
EP2C50	484-pin FineLine BGA	✓	✓
	672-pin FineLine BGA	✓	✓
EP2C70	672-pin FineLine BGA	✓	✓
	896-pin FineLine BGA	✓	✓

Table 10–3 lists the specific Cyclone II devices that support 64-bit and 32-bit PCI at 33 MHz.

Table 10–3. Cyclone II 33-MHz PCI Support (Part 1 of 2)

Device	Package	–6, –7 and –8 Speed Grades	
		64 Bits	32 Bits
EP2C5	144-pin TQFP	—	—
	208-pin PQFP	—	✓
	256-pin FineLine BGA	—	✓
EP2C8	144-pin TQFP	—	—
	208-pin PQFP	—	✓
	256-pin FineLine BGA	—	✓
EP2C15	256-pin FineLine BGA	—	✓
	484-pin FineLine BGA	✓	✓

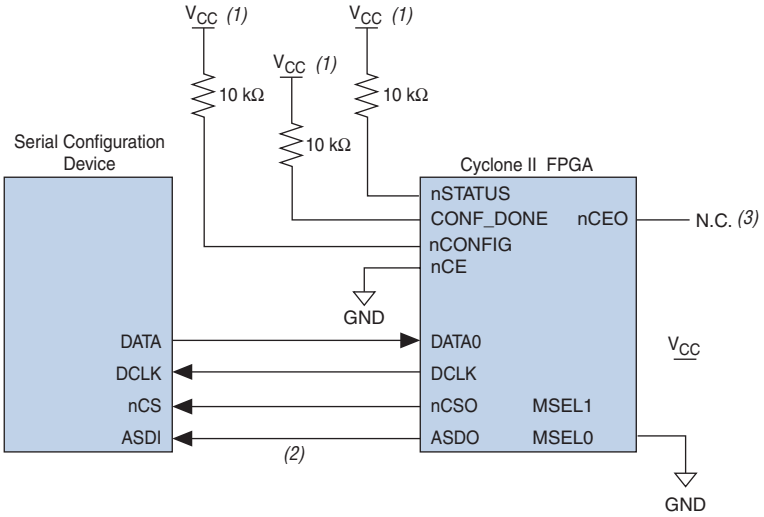
software makes it easy to use these I/O standards in Cyclone II device designs. After design compilation, the software also provides clear, visual representations of pads and pins and the selected I/O standards. Taking advantage of the support of these I/O standards in Cyclone II devices allows you to lower your design costs without compromising design flexibility or complexity.

References

For more information on the I/O standards referred to in this document, refer to the following sources:

- Stub Series Terminated Logic for 2.5-V (SSTL-2), JESD8-9A, Electronic Industries Association, December 2000.
- 1.5-V +/- 0.1-V (Normal Range) and 0.9-V - 1.6-V (Wide Range) Power Supply Voltage and Interface Standard for Non-terminated Digital Integrated Circuits, JESD8-11, Electronic Industries Association, October 2000.
- 1.8-V +/- 0.15-V (Normal Range) and 1.2-V - 1.95-V (Wide Range) Power Supply Voltage and Interface Standard for Non-terminated Digital Integrated Circuits, JESD8-7, Electronic Industries Association, February 1997.
- 2.5-V +/- 0.2-V (Normal Range) and 1.8-V to 2.7-V (Wide Range) Power Supply Voltage and Interface Standard for Non-terminated Digital Integrated Circuits, JESD8-5, Electronic Industries Association, October 1995.
- Interface Standard for Nominal 3-V/ 3.3-V Supply Digital Integrated Circuits, JESD8-B, Electronic Industries Association, September 1999.
- PCI Local Bus Specification, Revision 2.2, PCI Special Interest Group, December 1998.
- Electrical Characteristics of Low Voltage Differential Signaling (LVDS) Interface Circuits, ANSI/TIA/EIA-644, American National Standards Institute/Telecommunications Industry/Electronic Industries Association, October 1995.

Figure 13–3. Single Device AS Configuration



Notes to Figure 13–3:

(1) Connect the pull-up resistors to a 3.3-V supply.

(2) Cyclone II devices use the ASDO to ASDI path to control the configuration device.

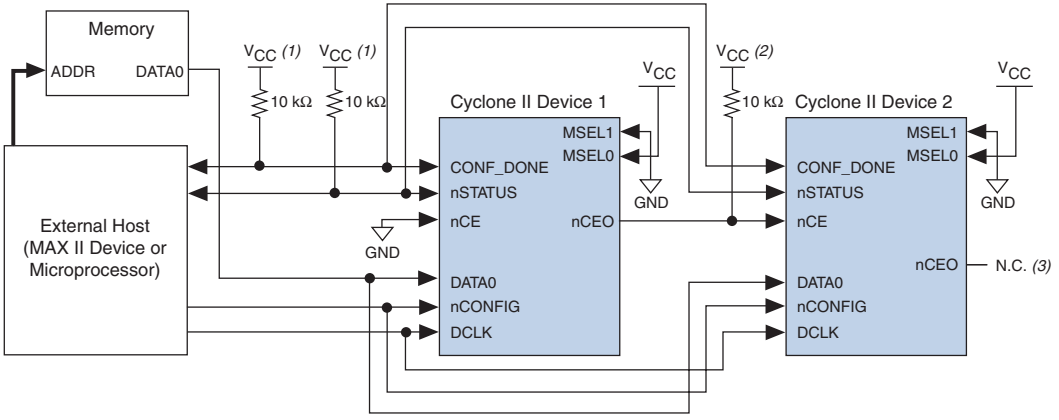
(3) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed another device's nCE pin.

Upon power-up, the Cyclone II device goes through a POR. During POR, the device resets, holds nSTATUS and CONF_DONE low, and tri-states all user I/O pins. After POR, which typically lasts 100 ms, the Cyclone II device releases nSTATUS and enters configuration mode when the external 10-kΩ resistor pulls the nSTATUS pin high. Once the FPGA successfully exits POR, all user I/O pins continue to be tri-stated. Cyclone II devices have weak pull-up resistors on the user I/O pins which are on before and during configuration.

The value of the weak pull-up resistors on the I/O pins that are on before and during configuration are available in the *DC Characteristics & Timing Specifications* chapter of the *Cyclone II Device Handbook*.

The configuration cycle consists of the reset, configuration, and initialization stages.

Figure 13–10. Multiple Device PS Configuration Using an External Host



Notes to Figure 13–10:

(1) The pull-up resistor should be connected to a supply that provides an acceptable input signal for all devices in the chain. V_{CC} should be high enough to meet the V_{IH} specification of the I/O on the devices and the external host.

(2) Connect the pull-up resistor to the V_{CCIO} supply voltage of I/O bank that the nCEO pin resides in.

(3) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed another device's nCE pin.

In multiple device PS configuration, connect the first Cyclone II device's nCE pin to GND and connect the nCEO pin to the nCE pin of the next Cyclone II device in the chain. Use an external 10-kΩ pull-up resistor to pull the Cyclone II device's nCEO pin high to its V_{CCIO} level to help the internal weak pull-up resistor when the nCEO pin feeds next Cyclone II device's nCE pin. The input to the nCE pin of the last Cyclone II device in the chain comes from the previous Cyclone II device. After the first device completes configuration in a multiple device configuration chain, its nCEO pin transitions low to activate the second device's nCE pin, which prompts the second device to begin configuration. The second device in the chain begins configuration within one clock cycle. Therefore, the MAX II device begins to transfer data to the next Cyclone II device without interruption. The nCEO pin is a dual-purpose pin in Cyclone II devices. You can leave the nCEO pin of the last device unconnected or use it as a user I/O pin after configuration if the last device in chain is a Cyclone II device.

The Quartus II software sets the Cyclone II device nCEO pin as a dedicated output by default. If the nCEO pin feeds the next device's nCE pin, you must make sure that the nCEO pin is not used as a user I/O after configuration. This software setting is in the **Dual-Purpose Pins** tab of the **Device & Pin Options** dialog box in Quartus II software.

Upon power-up, the Cyclone II device goes through a POR. During POR, the device reset, holds nSTATUS and CONF_DONE low, and tri-states all user I/O pins. After POR, which typically lasts 100 ms, the Cyclone II FPGA releases nSTATUS and enters configuration mode when this signal is pulled high by the external 10-kΩ resistor. Once the FPGA successfully exits POR, all user I/O pins continue to be tri-stated. Cyclone II devices have weak pull-up resistors on the user I/O pins which are on before and during configuration.

The configuration device also goes through a POR delay to allow the power supply to stabilize. The maximum POR time for EPC2 or EPC1 devices is 200 ms. The POR time for enhanced configuration devices can be set to 100 ms or 2 ms, depending on the enhanced configuration device's PORSEL pin setting. If the PORSEL pin is connected to ground, the POR delay is 100 ms. If the PORSEL pin is connected to V_{CC}, the POR delay is 2 ms. You must power the Cyclone II device before or during the enhanced configuration device POR time. During POR, the configuration device transitions its OE pin low. This low signal delays configuration because the OE pin is connected to the target device's nSTATUS pin. When the target and configuration devices complete POR, they both release the nSTATUS to OE line, which is then pulled high by a pull-up resistor.

When the power supplies have reached the appropriate operating voltages, the target FPGA senses the low-to-high transition on nCONFIG and initiates the configuration cycle. The configuration cycle consists of three stages: reset, configuration, and initialization.

The Cyclone II device does not have a PORSEL pin.

Reset Stage

While nCONFIG or nSTATUS is low, the device is in reset. You can delay configuration by holding the nCONFIG or nSTATUS pin low.

V_{CCINT} and V_{CCIO} of the banks where the configuration and JTAG pins reside need to be fully powered to the appropriate voltage levels in order to begin the configuration process.

When the nCONFIG signal goes high, the device comes out of reset and releases the nSTATUS pin, which is pulled high by a pull-up resistor. Enhanced configuration and EPC2 devices have an optional internal pull-up resistor on the OE pin. You can turn on this option in the Quartus II software from the **General** tab of the **Device & Pin Options** dialog box. If this internal pull-up resistor is not used, you need to connect an external 10-kΩ pull-up resistor to the OE and nSTATUS line. Once nSTATUS is released, the FPGA is ready to receive configuration data and the configuration stage begins.

PS Configuration Using a Download Cable

In PS configuration, an intelligent host (e.g., a PC) can use a download cable to transfer data from a storage device to the Cyclone II device. You can use the Altera USB-Blaster universal serial bus (USB) port download cable, MasterBlaster™ serial/USB communications cable, ByteBlaster II parallel port download cable, or the ByteBlasterMV™ parallel port as a download cable.

Upon power up, the Cyclone II device goes through POR, which lasts approximately 100 ms for non "A" devices. During POR, the device resets, holds nSTATUS low, and tri-states all user I/O pins. Once the FPGA successfully exits POR, the nSTATUS pin is released and all user I/O pins continue to be tri-stated.

The value of the weak pull-up resistors on the I/O pins that are on before and during configuration can be found in the *Cyclone II Device Handbook*.

The configuration cycle consists of three stages: reset, configuration, and initialization. While the nCONFIG or nSTATUS pins are low, the device is in reset. To initiate configuration in this scheme, the download cable generates a low-to-high transition on the nCONFIG pin.

Make sure V_{CCINT} and V_{CCIO} for the banks where the configuration and JTAG pins reside are powered to the appropriate voltage levels in order to begin the configuration process.

When nCONFIG transitions high, the Cyclone II device comes out of reset and begins configuration. The Cyclone II device releases the open-drain nSTATUS pin, which is then pulled high by an external 10-kΩ pull-up resistor. Once nSTATUS transitions high, the Cyclone II device is ready to receive configuration data. The programming hardware or download cable then transmits the configuration data one bit at a time to the device's DATA0 pin. The configuration data is clocked into the target device until CONF_DONE goes high. The CONF_DONE pin must have an external 10-kΩ pull-up resistor in order for the device to initialize.

When using a download cable, you cannot use the **Auto-restart configuration after error** option. You must manually restart configuration in the Quartus II software when an error occurs. Additionally, you cannot use the **Enable user-supplied start-up clock (CLKUSR)** option when programming the FPGA using the Quartus II programmer and download cable. This option is disabled in the SOF. Therefore, if you turn on the CLKUSR option, you do not need to provide a clock on CLKUSR when you are configuring the FPGA with the

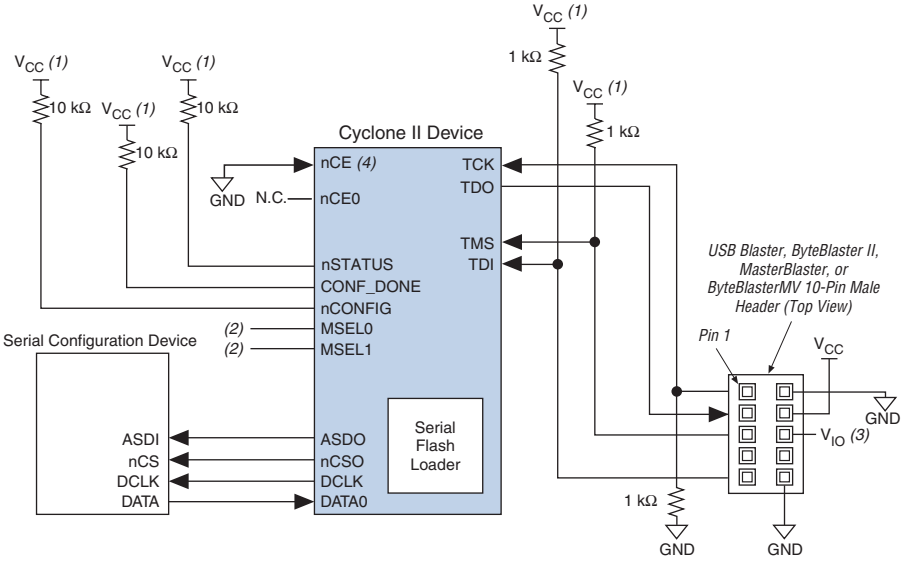
When designing a Cyclone II board for JTAG configuration, use the guidelines in Table 13–10 for the placement of the dedicated configuration pins.

Table 13–10. Dedicated Configuration Pin Connections During JTAG Configuration

Signal	Description
nCE	On all Cyclone II devices in the chain, nCE should be driven low by connecting it to ground, pulling it low via a resistor, or driving it by some control circuitry. For devices that are also in multiple device AS, or PS configuration chains, the nCE pins should be connected to GND during JTAG configuration or JTAG configured in the same order as the configuration chain.
nCEO	On all Cyclone II devices in the chain, nCEO can be used as a user I/O or connected to the nCE of the next device. If nCEO is connected to the nCE of the next device, the nCEO pin must be pulled high to V_{CCIO} by an external 10-kΩ pull-up resistor to help the internal weak pull-up resistor. If the nCEO pin is not connected to the nCE pin of the next device, you can use it as a user I/O pin after configuration.
MSEL	These pins must not be left floating. These pins support whichever non-JTAG configuration is used in production. If only JTAG configuration is used, you should tie these pins to ground.
nCONFIG	Driven high by connecting to V_{CC}, pulling up via a resistor, or driven high by some control circuitry.
nSTATUS	Pull to V_{CC} via a 10-kΩ resistor. When configuring multiple devices in the same JTAG chain, each nSTATUS pin should be pulled up to V_{CC} individually. nSTATUS pulling low in the middle of JTAG configuration indicates that an error has occurred.
CONF_DONE	Pull to V_{CC} via a 10-kΩ resistor. When configuring multiple devices in the same JTAG chain, each CONF_DONE pin should be pulled up to V_{CC} individually. CONF_DONE going high at the end of JTAG configuration indicates successful configuration.
DCLK	Should not be left floating. Drive low or high, whichever is more convenient on your board.

Figure 13–23 shows JTAG configuration of a Cyclone II device with a microprocessor.

Figure 13–25. JTAG Configuration of a Single Device Using a Download Cable



Notes to Figure 13–25:

(1) The pull-up resistor should be connected to the same supply voltage as the USB Blaster, MasterBlaster (V_{IO} pin), ByteBlaster II, or ByteBlasterMV cable.

(2) The `nCONFIG`, `MSEL[1..0]` pins should be connected to support a non-JTAG configuration scheme. If only JTAG configuration is used, connect `nCONFIG` to V_{CC}, and `MSEL[1..0]` to ground. Pull `DCLK` either high or low, whichever is convenient on your board.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} should match the device's V_{CCIO}. Refer to the *MasterBlaster Serial/USB Communications Cable Data Sheet* for this value. In the ByteBlasterMV cable, this pin is a no connect. In the USB Blaster and ByteBlaster II cables, this pin is connected to `nCE` when it is used for active serial programming, otherwise it is a no connect.

(4) `nCE` must be connected to GND or driven low for successful JTAG configuration.

ISP of Serial Configuration Device

In the second stage, the serial flash loader design in the master Cyclone II device allows you to write the configuration data for the device chain into the serial configuration device by using the Cyclone II JTAG interface. The JTAG interface sends the programming data for the serial configuration device to the Cyclone II device first. The Cyclone II device then uses the ASMI pins to transmit the data to the serial configuration device.

operate the TAP controller, and the TDI and TDO pins provide the serial path for the data registers. The TDI pin also provides data to the instruction register, which then generates control logic for the data registers.

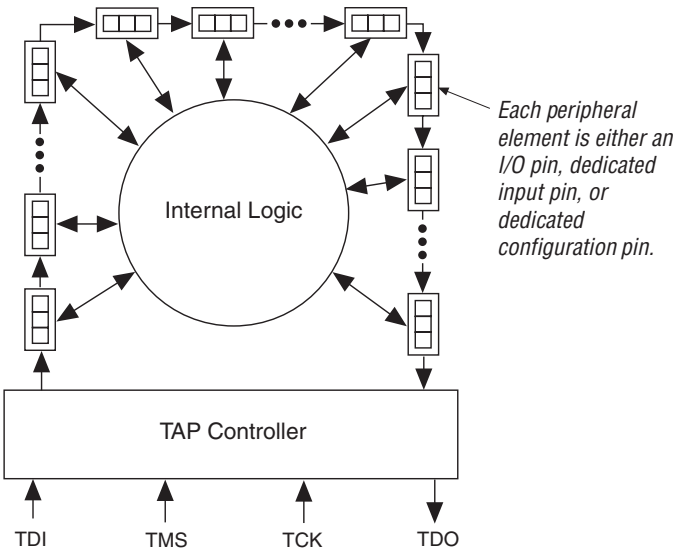
IEEE Std. 1149.1 Boundary-Scan Register

The boundary-scan register is a large serial shift register that uses the TDI pin as an input and the TDO pin as an output. The boundary-scan register consists of 3-bit peripheral elements that are associated with Cyclone II I/O pins. You can use the boundary-scan register to test external pin connections or to capture internal data.

See the *Configuration & Testing* chapter in Volume 1 of the *Cyclone II Device Handbook* for the Cyclone II device boundary-scan register lengths.

Figure 14–3 shows how test data is serially shifted around the periphery of the IEEE Std. 1149.1 device.

Figure 14–3. Boundary-Scan Register



Boundary-Scan Cells of a Cyclone II Device I/O Pin

The Cyclone II device 3-bit boundary-scan cell (BSC) consists of a set of capture registers and a set of update registers. The capture registers can connect to internal device data via the OUTJ and OEJ signals, and connect